

(1,27 mm) .050"

SEAMP, SEAMI SERIES

# HIGH SPEED/HIGH DENSITY OPEN PIN FIELD

Mates with:  
SEAF, SEAF-RA-GP

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?SEAMP](http://www.samtec.com?SEAMP)

**Insulator Material:** Natural LCP  
**Contact Material:** Copper Alloy  
**Operating Temp Range:** -55°C to +125°C

**Current Rating:** 2.5 A per pin  
(6 adjacent pins powered)

**Plating:** Au or Sn over  
50 μ" (1,27 μm) Ni

**Contact Resistance:** 8.7 mΩ

**Working Voltage:** 215 VAC

**RoHS Compliant:** Yes

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



**Note:** Compliant pin fixture  
CAT-SEAMP-XX-XX.  
Patent Pending.

SEAMP

NO. OF POSITIONS  
PER ROW

02.0

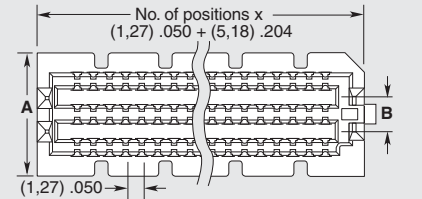
PLATING  
OPTIONNO. OF  
ROWS

OPTION

SEAMP  
= Press Fit

-10, -20, -30, -40, -50

| NO. OF ROWS | A               | B              |
|-------------|-----------------|----------------|
| -04         | (7,06)<br>.278  | (2,54)<br>.100 |
| -06         | (9,60)<br>.378  | (2,54)<br>.100 |
| -08         | (12,14)<br>.478 | (5,08)<br>.200 |
| -10         | (14,68)<br>.578 | (7,62)<br>.300 |



-L  
= 10 μ" (0,25 μm)  
Gold on  
contact area,  
Matte Tin on tail

-S  
= 30 μ" (0,76 μm)  
Gold on  
contact area,  
Matte Tin on tail

-04  
= Four Rows

-06  
= Six Rows

-08  
= Eight Rows

-10  
= Ten Rows

-GP  
= Guide  
Post  
(Mates with  
SEAF-RA-  
GP only)

-TR  
= Tape  
& Reel

| MATED HEIGHTS*   |                 |             |
|------------------|-----------------|-------------|
| SEAMP LEAD STYLE | SEAF LEAD STYLE |             |
| -05.0            | -06.0           | -06.5       |
| -02.0            | 7 mm            | 8 mm 8.5 mm |

\*Processing conditions will affect mated height.

| SEAMP/SEAF-RA               | Rated @ 3dB Insertion Loss* |
|-----------------------------|-----------------------------|
| Single-Ended Signaling      | 11 GHz / 22 Gbps            |
| Differential Pair Signaling | 11 GHz / 22 Gbps            |

\*Test board losses de-embedded from performance data.

Complete test data available at [www.samtec.com?SEAMP](http://www.samtec.com?SEAMP) or contact [sig@samtec.com](mailto:sig@samtec.com)

**Processing:** Application tooling and one ton minimum press required. Contact [ATG@samtec.com](mailto:ATG@samtec.com) for more information.

Mates with:  
SEAF

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?SEAMI](http://www.samtec.com?SEAMI)

**Insulator Material:** Black LCP

**Contact Material:** Copper Alloy

**Operating Temp Range:** Testing Now!

**Plating:** Au or Sn over

50 μ" (1,27 μm) Ni

**Contact Resistance:** Testing Now!

**Working Voltage:** Testing Now!

**RoHS Compliant:** Yes

**Lead-Free Solderable:** Yes

## ALSO AVAILABLE (MOQ Required)

- Other plating options
  - 20 & 30 pins per row
  - 04 & 06 rows
- Contact Samtec.

**Note:** Patented

**Note:** Some sizes, styles and options are non-standard, non-returnable.

SEAMI

NO. PINS  
PER ROW

11.0

PLATING  
OPTIONNO. OF  
ROWSSOLDER  
TYPE

A

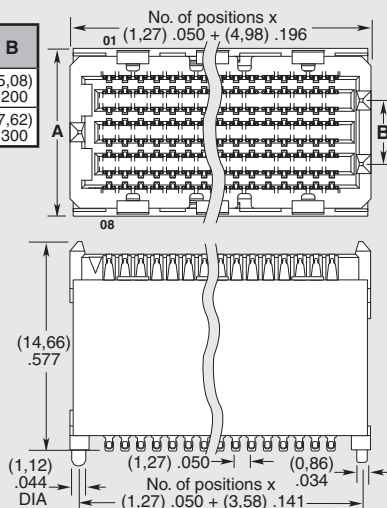
K

TR

SEAMI  
= 85Ω tuned

-40, -50

| NO. OF ROWS | A               | B              |
|-------------|-----------------|----------------|
| -08         | (13,41)<br>.528 | (5,08)<br>.200 |
| -10         | (15,95)<br>.628 | (7,62)<br>.300 |



-L  
= 10 μ" (0,25 μm)  
Gold on  
contact area,  
Matte Tin on  
solder tail

-S  
= 30 μ" (0,76 μm)  
Gold on  
contact area,  
Matte Tin on  
solder tail

-08  
= Eight Rows

-10  
= Ten Rows

-1  
= Tin/Lead  
Alloy  
Solder  
Charge

-2  
= Lead-Free  
Solder  
Charge

-A  
= Alignment Pins

-K  
= Polyimide film  
Pick & Place Pad

-TR  
= Tape & Reel

| MATED HEIGHTS*   |                 |               |
|------------------|-----------------|---------------|
| SEAMI LEAD STYLE | SEAF LEAD STYLE |               |
| -11.0            | -05.0           | -06.0 -06.5   |
| -11.0            | 16 mm           | 17 mm 17.5 mm |

\*Processing conditions will affect mated height.

| SEAMI/SEAF<br>16 mm Stack Height | Rated @ 3dB Insertion Loss* |
|----------------------------------|-----------------------------|
| Single-Ended Signaling           | 14 GHz / 28 Gbps            |
| Differential Pair Signaling      | 16.5 GHz / 33 Gbps          |

\*Test board losses de-embedded from performance data.

Complete test data available at [www.samtec.com?SEAMI](http://www.samtec.com?SEAMI) or contact [sig@samtec.com](mailto:sig@samtec.com)

28+  
Gbps